Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

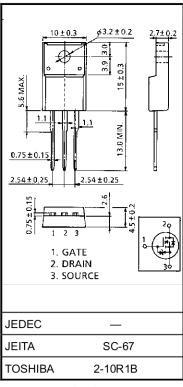
2SK2750

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance : RDS (ON) = 1.7 Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 3.0 \text{ S (typ.)}$ • Low leakage current : IDSS = 100 μ A (max) (VDS = 600 V) • Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (VDS} = 10 \text{ V, ID} = 1 \text{ mA}$)

Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	600	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	ΙD	3.5	А
	Pulse (Note 1)	I_{DP}	14	А
Drain power dissipatio	n (Tc = 25°C)	P _D	35	W
Single pulse avalanche energy (Note 2)		E _{AS}	201	mJ
Avalanche current		I _{AR}	3.5	А
Repetitive avalanche energy (Note 3)		E _{AR}	3.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

1

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.57	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 28.8 mH, R_{G} = 25 Ω , I_{AR} = 3.5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

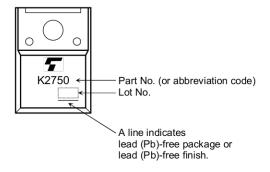
Electrical Characteristics (Ta = 25°C)

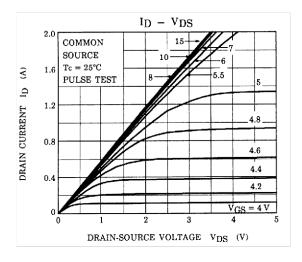
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1.8 A	_	1.7	2.2	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 1.8 A	2.0	3.0	_	S
Input capacitano	е	C _{iss}		_	800	_	
Reverse transfe	capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	6	_	pF
Output capacitance		Coss		_	65	_	
Switching time	Rise time	t _r	$V_{GS} \xrightarrow[0V]{I_{D}=1.8A} \\ V_{GS} \xrightarrow[0V]{R_{L}=111\Omega} \\ V_{DD} = 200V$ $Duty \leq 1\%, \ t_{W} = 10 \mu s$	_	15	_	ns
	Turn-on time	t _{on}		_	50	_	
	Fall time	t _f		_	15	_	115
	Turn-off time	t _{off}		_	85	_	
Total gate charg plus gate-drain)		Qg			20		
Gate-source charge Gate-drain ("miller") Charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3.5 \text{ A}$	_	10	_	nC
		Q _{gd}			10	_	

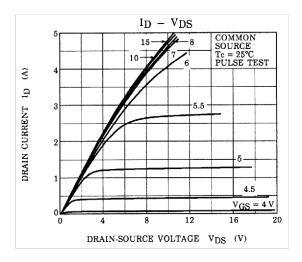
Source-Drain Ratings and Characteristics (Ta = 25°C)

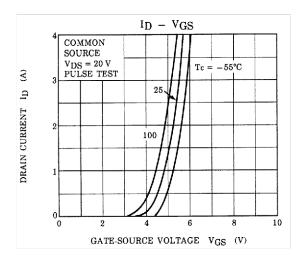
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	14	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 3.5 A, V _{GS} = 0 V		_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 3.5 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs		1400		ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / μs		9	_	μC

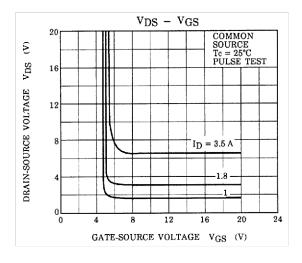
Marking

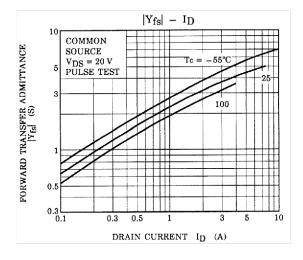


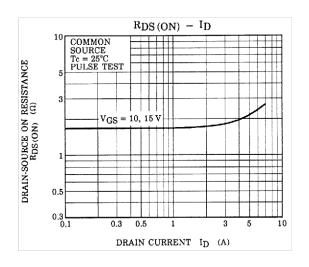


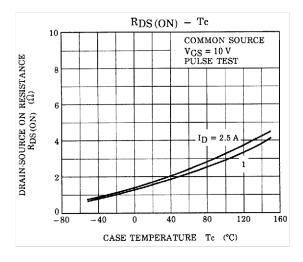


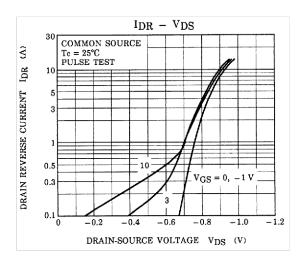


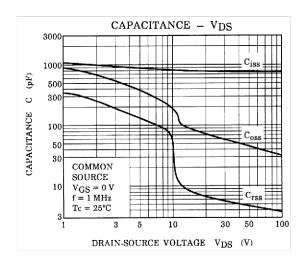


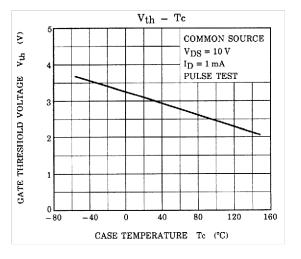


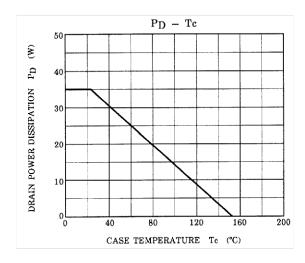




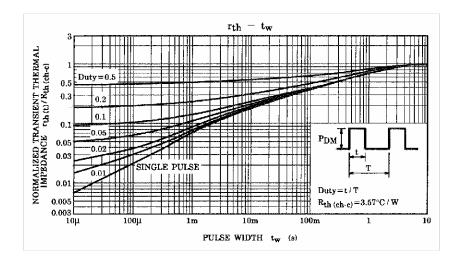


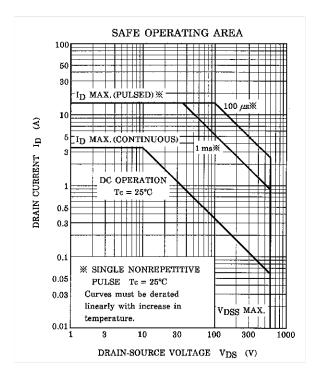


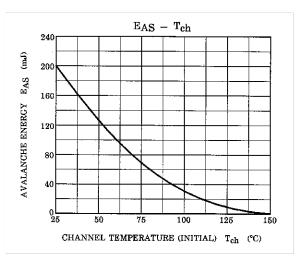


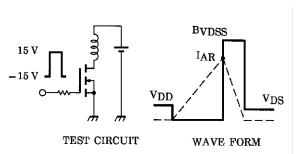


4









$$\begin{split} R_G &= 25~\Omega \\ V_{DD} &= 90~V,\, L = 28.8~mH \end{split}$$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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